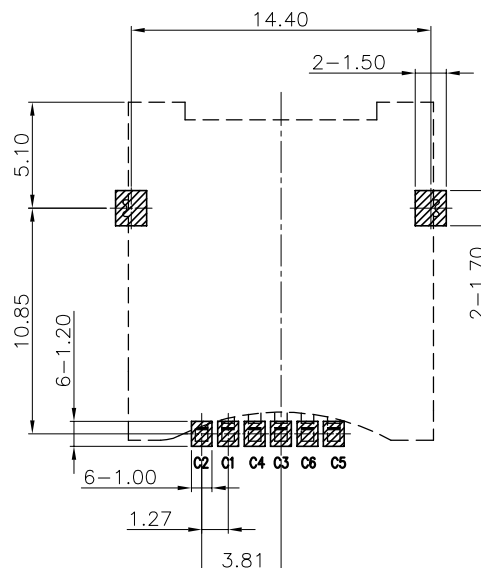
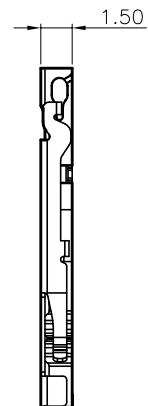
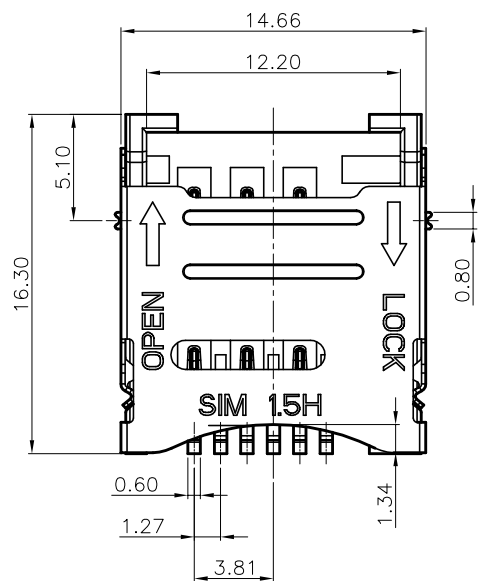


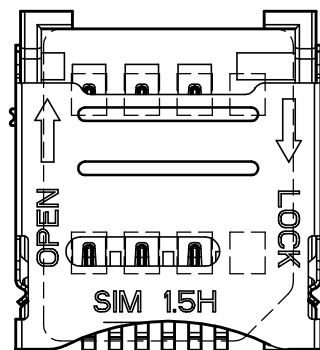
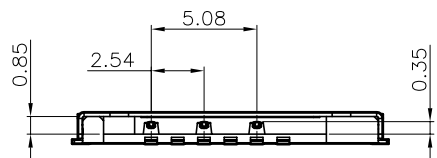
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2013/02/29



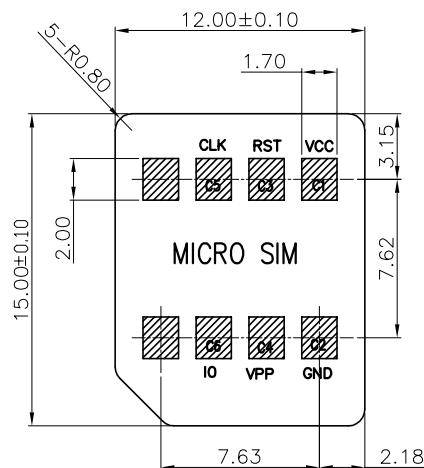
RECOMMEND PCB LAYOUT

TOLERANCE: ± 0.05

TOP VIEW



插卡示意图



MATERIALS

1. HOUSING :THERMOPLASTIC (UL 94V-0) .
2. TERMINAL : COPPER ALLOY.
PLATING : PLATING SEE TABLE.
3. LANDING : SUS,TIN PLATED OVERALL.
4. SHELL :SUS.

SPECIFICATION

1. CURRENT RATING : 1 A. MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE :
250V AC R.M.S. FOR 1 MINUTE.
3. INSULATION RESISTANCE : 100M Ω MIN.AT 5V DC.
4. CONTACT RESISTANCE : 50m Ω MAX.
5. OPERATING TEMPERATURE : -30°C TO +80°C.
6. DURABILITY:3000 CYCLES.

DESCRIPTION OF PLATING ON TERMINALS			
NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	H	G/F + TIN

PIN NO		NAME		GENERAL TOLERANCE		DWG NO.	JYSA1205-001	APPD:	WIND	Scale	1:1
C1		VCC		X. ± 0.45		Title	1.5H MICRO SIM CARD 6PIN 掀盖式	CHKD:		UNIT	mm
C2		GND		x. ± 5				DR:			
C3		RST		.XX ± 0.25		Part NO.	JYS-SIM150-061	Date	2013/02/29		
C4		VPP		.xx ± 2		Date		2013/02/29			
C5		CLK		.XXX ± 0.15		Date		2013/02/29			
C6		IO		.xxx ± 0.5		Date					
SHEET		1/1									

JYSCONN Shenzhen
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